

IGBT MODULE (S series)

1200V / 25A / PIM



■ Features

- Low $V_{CE(sat)}$
- Compact package
- P.C. board mount
- Converter diode bridge, Dynamic brake circuit

■ Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

■ Maximum ratings and characteristics

● Absolute maximum ratings ($T_c=25^\circ\text{C}$ unless without specified)

Item	Symbol	Condition	Rating	Unit
Inverter	Collector-Emitter voltage	V_{CES}	1200	V
	Gate-Emitter voltage	V_{GES}	± 20	V
	Collector current	I_C	$T_c=25^\circ\text{C}$	35
				25
		I_{CP}	1ms	70
				50
	- I_C		25	A
	Collector power dissipation	P_C	180	W
	Collector-Emitter voltage	V_{CES}	1200	V
	Gate-Emitter voltage	V_{GES}	± 20	V
Brake	Collector current	I_C	$T_c=25^\circ\text{C}$	25
				15
		I_{CP}	1ms	50
				30
	Collector power dissipation	P_C	110	W
	Repetitive peak reverse voltage	V_{RRM}	1200	V
Converter	Repetitive peak reverse voltage	V_{RRM}	1600	V
	Average output current	I_O	50Hz/60Hz sine wave	A
	Surge current (Non-Repetitive)	I_{FSM}	$T_j=150^\circ\text{C}, 10\text{ms}$	260
	I^2t (Non-Repetitive)	I^2t		338
	Operating junction temperature	T_j		$^\circ\text{C}$
Storage temperature		T_{STG}	-40 to +125	$^\circ\text{C}$
Isolation voltage	between terminal and copper base *2	V_{ISO}	AC : 1 minute	AC 2500
	between thermistor and others *3			AC 2500
Mounting screw torque			3.5 *1	N·m

*1 Recommendable value : 2.5 to 3.5 N·m (M5)

*2 All terminals should be connected together when isolation test will be done.

*3 Terminal 8 and 9 should be connected together. Terminal 1 to 7 and 10 to 24 should be connected together and shorted to copper base.

● Electrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified)

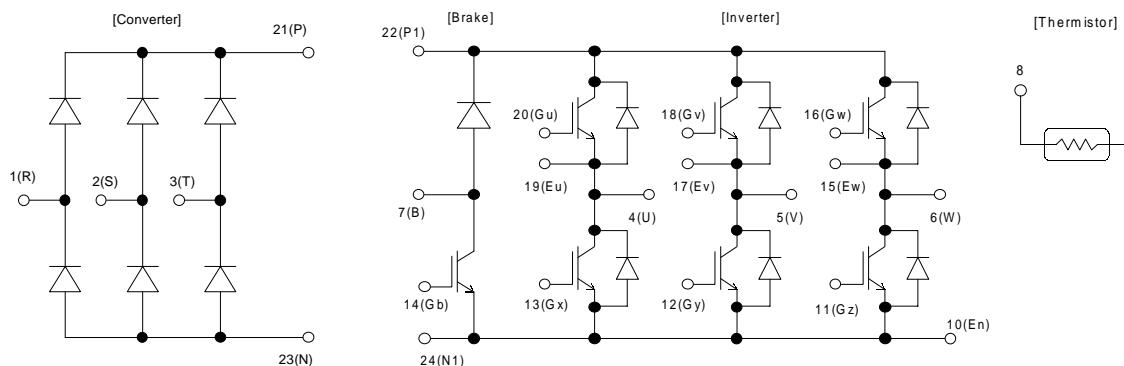
Item	Symbol	Condition	Characteristics			Unit
			Min.	Typ.	Max.	
Inverter	Zero gate voltage collector current	I_{CES}	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}$			1.0 mA
	Gate-Emitter leakage current	I_{GES}	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}$			0.2 μA
	Gate-Emitter threshold voltage	$V_{GE(\text{th})}$	$V_{CE}=20\text{V}, I_C=25\text{mA}$	5.5	7.2	8.5 V
	Collector-Emitter saturation voltage	$V_{CE(\text{sat})}$	$V_{GE}=15\text{V}, I_C=25\text{A}$	chip terminal	2.1	
					2.2	2.6
	Input capacitance	C_{IES}	$V_{GE}=0\text{V}, V_{CE}=10\text{V}, f=1\text{MHz}$		3000	pF
	Turn-on time	t_{on}	$V_{CC}=600\text{V}$		0.35	μs
		t_r	$I_C=25\text{A}$		0.25	
		t_{ri}	$V_{GE}=\pm 15\text{V}$		0.1	
	Turn-off	t_{off}	$R_G=51\Omega$		0.45	1.0
		t_f			0.08	0.3
Brake	Forward on voltage	V_F	$I_F=25\text{A}$	chip	2.3	
				terminal	2.4	3.2
	Reverse recovery time of FRD	t_{rr}	$I_F=25\text{A}$			0.35 μs
	Zero gate voltage collector current	I_{CES}	$V_{CES}=1200\text{V}, V_{GE}=0\text{V}$			1.0 mA
	Gate-Emitter leakage current	I_{GES}	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}$			0.2 μA
	Collector-Emitter saturation voltage	$V_{CE(\text{sat})}$	$I_C=15\text{A}, V_{GE}=15\text{V}$	chip	2.1	
				terminal	2.2	2.6
	Turn-on time	t_{on}	$V_{CC}=600\text{V}$		0.35	μs
		t_r	$I_C=15\text{A}$		0.25	
	Turn-off time	t_{off}	$V_{GE}=\pm 15\text{V}$		0.45	1.0
Converter		t_f	$R_G=82\Omega$		0.08	0.3
	Reverse current	I_{RRM}	$V_R=1200\text{V}$			1.0 mA
	Forward on voltage	V_{FM}	$I_F=25\text{A}$	chip	1.1	
				terminal	1.2	1.5
Thermistor	Reverse current	I_{RRM}	$V_R=1600\text{V}$			1.0 mA
	Resistance	R	$T=25^\circ\text{C}$		5000	Ω
			$T=100^\circ\text{C}$		465	
	B value	B	$T=25/50^\circ\text{C}$	3305	3375	K

● Thermal resistance Characteristics

Item	Symbol	Condition	Characteristics			Unit
			Min.	Typ.	Max.	
Thermal resistance (1 device)	$R_{th(j-c)}$	Inverter IGBT			0.69	$^\circ\text{C/W}$
		Inverter FWD			1.30	
		Brake IGBT			1.14	
		Converter Diode			0.90	
Contact thermal resistance *	$R_{th(c-f)}$	With thermal compound		0.05		

* This is the value which is defined mounting on the additional cooling fin with thermal compound

■ Equivalent Circuit Schematic



■ Outline Drawings, mm

